

Integrated Circuit Package Structure with Heat Dissipating Design

Abstract

An integrated circuit (IC) package structure with heat dissipation design. The IC chip is disposed on a package substrate and a power ring structure surrounds the chip. Due to the relatively large surface area of the power ring structure near the high heat zone of the IC chip, the contact area between the power ring structure and package substrate is enlarged. The power ring structure is connected to the isoelectric conductive layer of a multi-layer circuit board via an electric connection path, thereby enhancing heat dissipation.